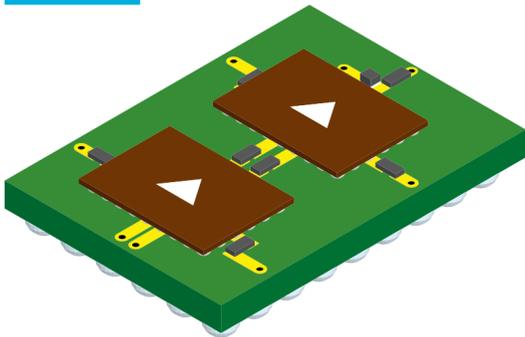


硅电容及硅基板方案

用于光模块

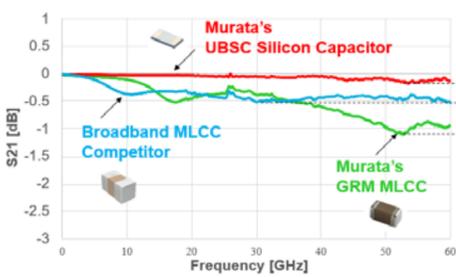
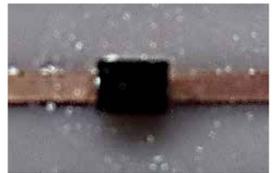


应用



适用于信号线上隔直，耦合的表面贴装超宽频硅电容

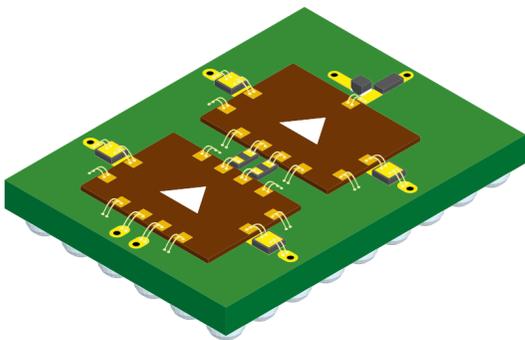
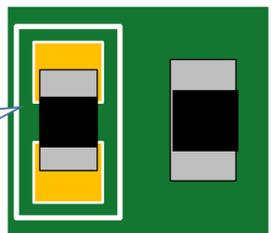
- 最高220GHz的超宽频性能
- 在旁路接地模式下，超低ESL和ESR



宽频范围内超低插损

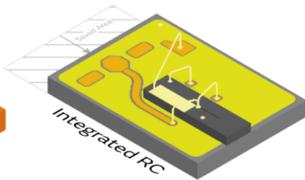
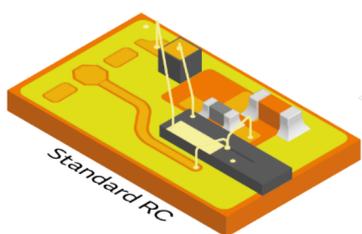
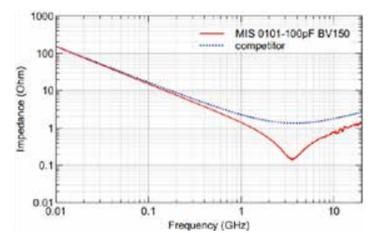
更小的实装面积

MLCC Si-Cap



打线退耦硅电容

- 小封装，大容量
- 高频下超低ESL和ESR
- 适合打线的完美的电极平坦度
- 低厚度，高可靠性



定制硅基板

- 高频下更低的插损
- 超小型,低厚度
- 高可靠性
- 总成本降低
- 封装方式多样化
- 可定制化

